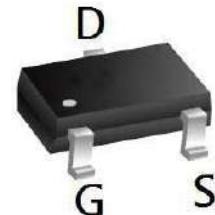


N-Ch 30V Fast Switching MOSFETs

Features:

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent Cdv/dt effect decline
- ★ Advanced high cell density Trench technology

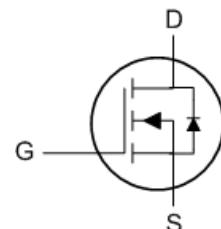


Description:

SOT23S Pin Configuration

The KN3502S is the high cell density trenched N-ch MOSFETs, which provides excellent RDSON and efficiency for most of the small power switching and load switch applications.

The KN3502S meet the RoHS and Green Product requirement with full function reliability approved.



Product Summary

BVDSS	RDS _{ON}	ID
30V	27mΩ	5.8A

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _A =25°C	Continuous Drain Current	5.8	A
I _D @T _A =70°C	Continuous Drain Current	4.9	A
I _{DM}	Pulsed Drain Current ²	30	A
P _D @T _A =25°C	Total Power Dissipation ³	1	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	125	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)	---	85	°C/W

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$, $I_D=1\text{mA}$	---	0.029	---	$\text{V}/^{\circ}\text{C}$
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{GS}=10\text{V}$, $I_D=5.8\text{A}$	---	---	27	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=5\text{A}$	---	---	32	
		$V_{GS}=2.5\text{V}$, $I_D=4\text{A}$	---	---	40	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	0.5	---	1.2	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-2.82	---	$\text{mV}/^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	uA
		$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$, $T_J=55\text{ }^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=5\text{A}$	---	25	---	S
R_g	Gate Resistance	$V_{DS}=0\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	1.5	---	Ω
Q_g	Total Gate Charge (4.5V)	$V_{DS}=15\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=5.8\text{A}$	---	11.5	---	nC
Q_{gs}	Gate-Source Charge		---	1.6	---	
Q_{gd}	Gate-Drain Charge		---	2.9	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=15\text{V}$, $V_{GS}=10\text{V}$, $R_G=3\Omega$ $I_D=5\text{A}$	---	5	---	ns
T_r	Rise Time		---	47.	---	
$T_{d(off)}$	Turn-Off Delay Time		---	26	---	
T_f	Fall Time		---	8	---	
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	860	---	pF
C_{oss}	Output Capacitance		---	84	---	
C_{rss}	Reverse Transfer Capacitance		---	70	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,4}	$V_G=V_D=0\text{V}$, Force Current	---	---	5.8	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.Repetitive rating, pulse width limited by junction temperature.
- 3.The power dissipation is limited by $150\text{ }^{\circ}\text{C}$ junction temperature
- 4.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

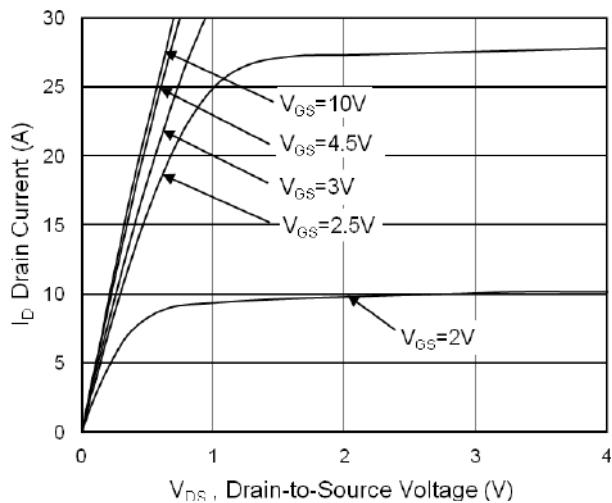


Fig.1 Typical Output Characteristics

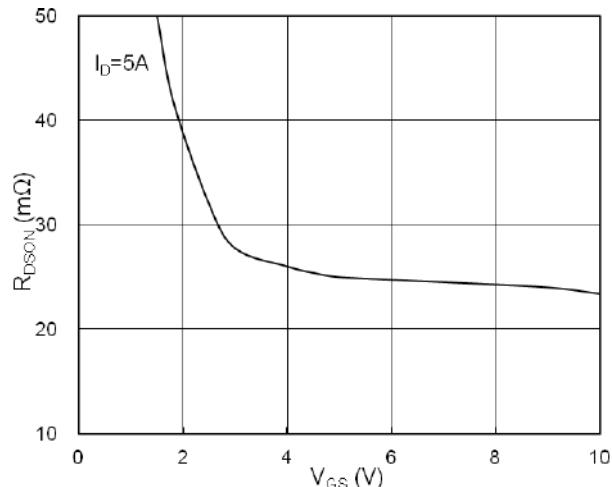


Fig.2 On-Resistance vs. Gate-Source

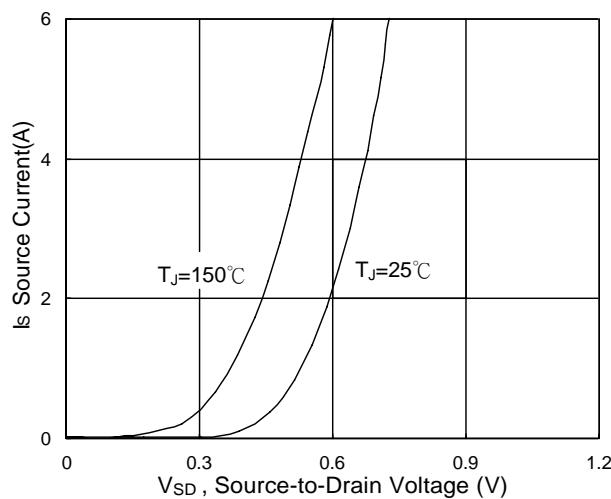


Fig.3 Forward Characteristics Of Reverse

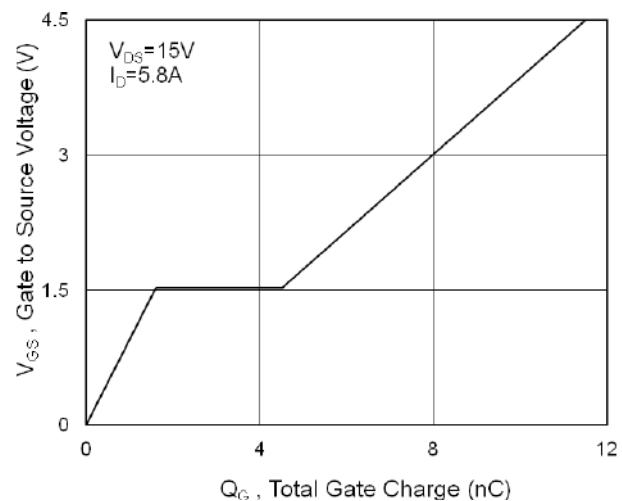


Fig.4 Gate-Charge Characteristics

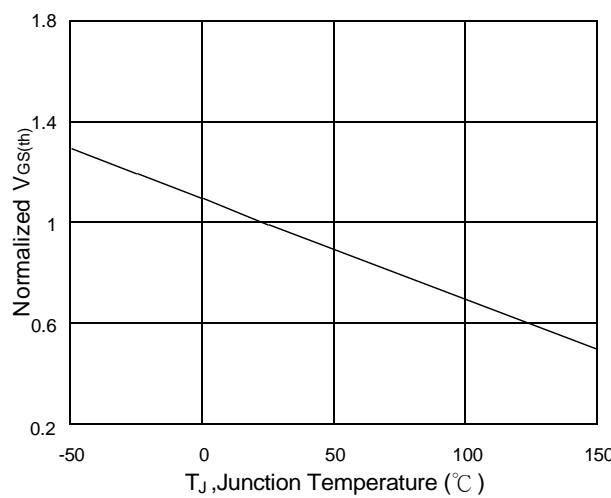


Fig.5 Normalized V_{GS(th)} vs. T_J

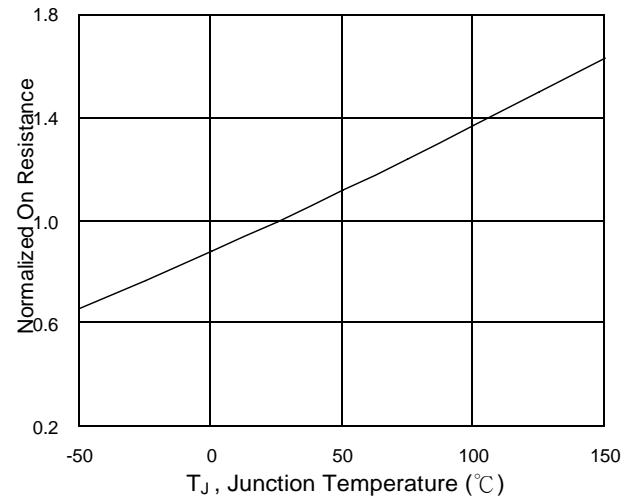


Fig.6 Normalized R_{DSON} vs. T_J

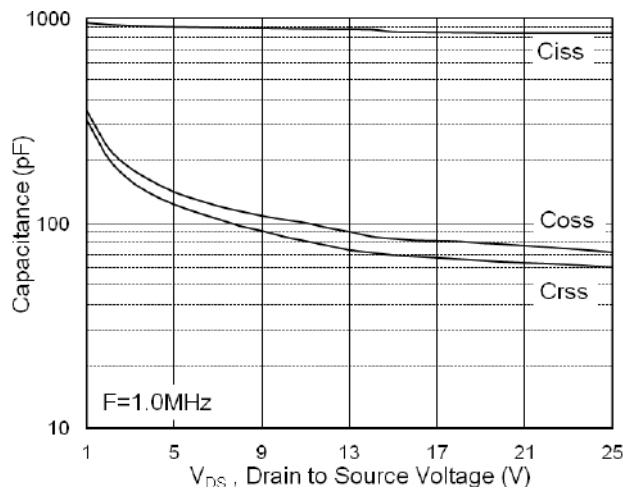


Fig.7 Capacitance

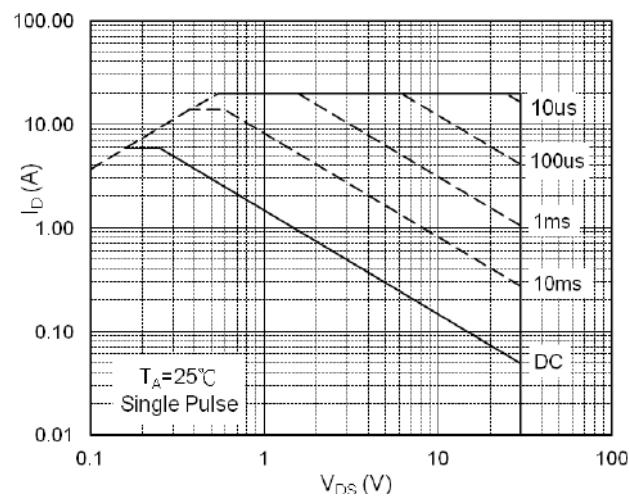


Fig.8 Safe Operating Area

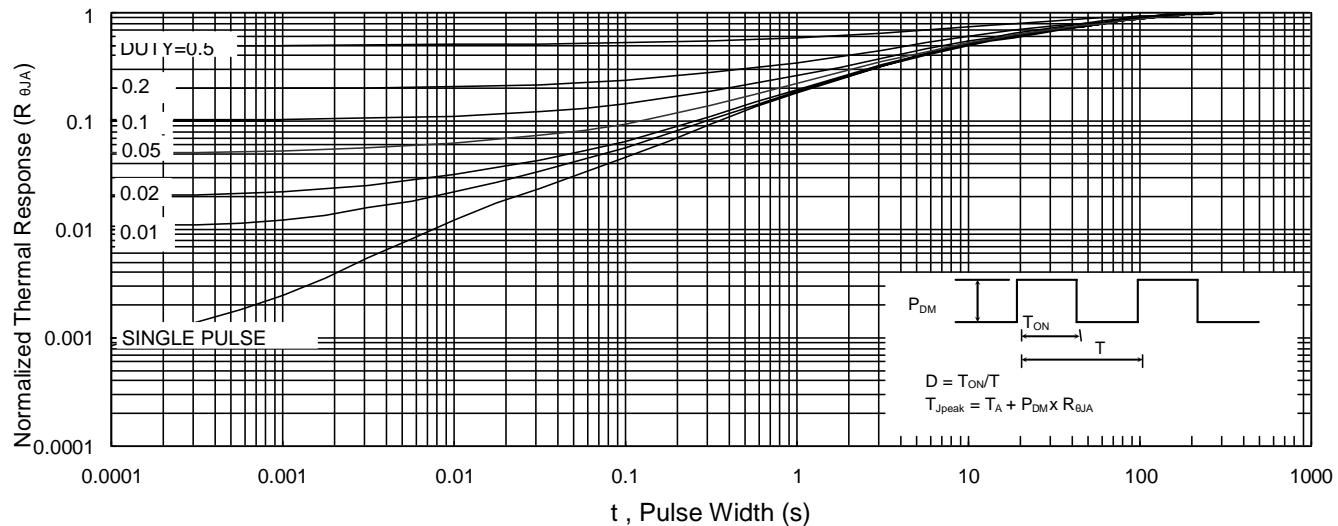


Fig.9 Normalized Maximum Transient Thermal Impedance

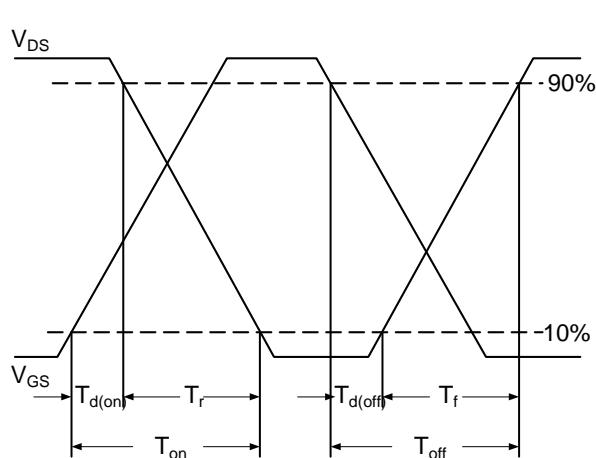


Fig.10 Switching Time Waveform

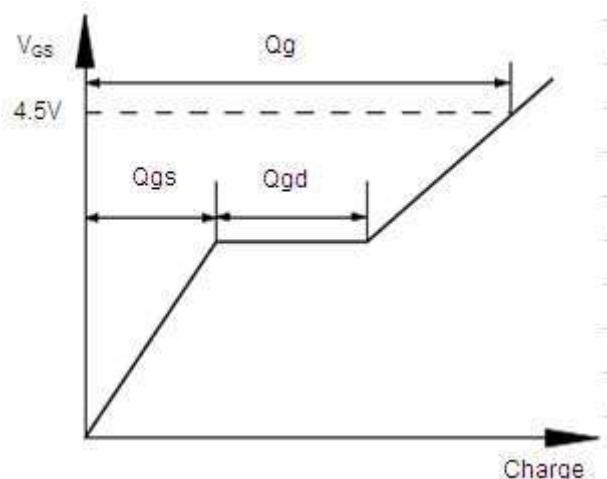
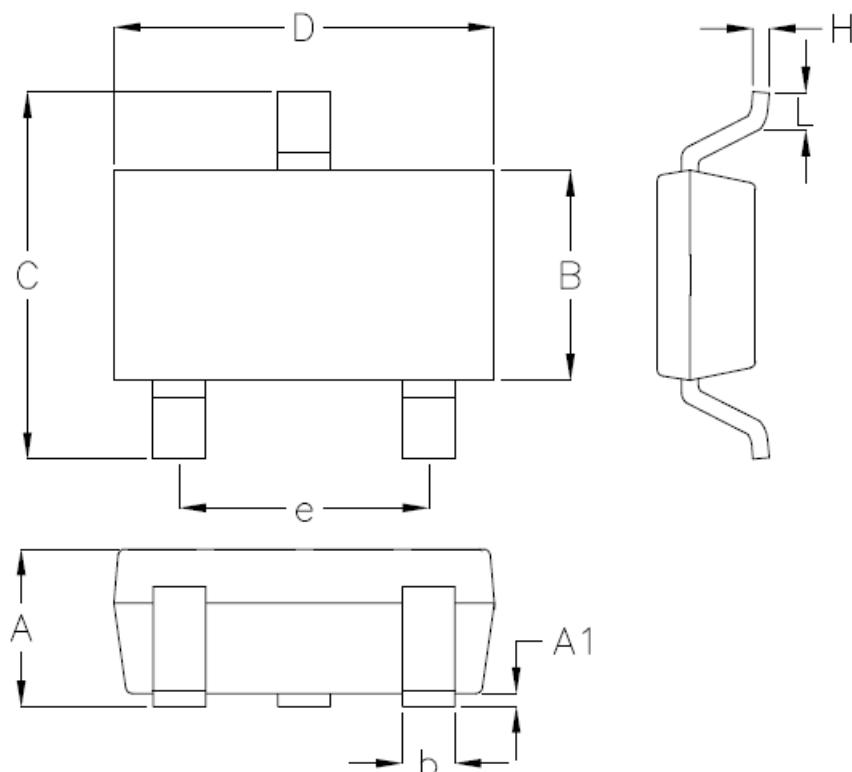


Fig.11 Gate Charge Waveform

SOT-23S Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.890	1.295	0.035	0.051
A1	0.000	0.152	0.000	0.006
B	1.200	1.400	0.047	0.055
b	0.300	0.508	0.012	0.020
C	2.100	2.640	0.083	0.104
D	2.692	3.099	0.106	0.122
e	1.793	2.007	0.070	0.079
H	0.080	0.254	0.003	0.010
L	0.300	0.610	0.012	0.024